

## *Sensors and Materials*

### **Special Issue on Mechanical and Thermal Reliability of Micro/Nanomaterials**

#### Call for Papers

Owing to the rapid progress of recent semiconductor fabrication technologies, precisely shaped mechanical and electrical components in semiconductor devices and micro-electromechanical systems (MEMS) can be produced. To improve their performance and reliability, the mechanical and thermal properties of structural materials at the micro/nanoscale should be measured experimentally, and then the knowledge obtained in experiments should be reflected in the design of these devices. This special issue will focus on state-of-the-art experimental technologies for measuring the mechanical and thermal properties of silicon and related materials.

#### **Scope:**

- mechanical and thermal properties
- silicon-related materials, metals, and polymers
- reliability of semiconductor devices and MEMS
- experimental technologies
- size effects and process effects

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**Publication date (planned):** First half of 2019

**Journal website:** <http://myukk.org/>

**Guest Editors:** Takahiro Namazu (Aichi Institute of Technology)  
and Shugo Miyake (Kobe City College of Technology)

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2. Email to MYU K.K. ([myukk@myu-inc.jp](mailto:myukk@myu-inc.jp))

#### **(Attention)**

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If you have any questions, please feel free to contact the editorial staff at the address below.

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